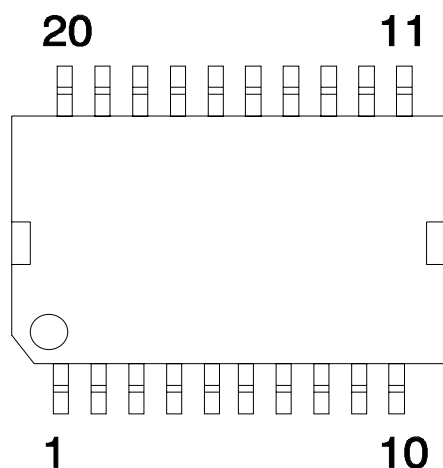




## Pin Configuration (Top view)



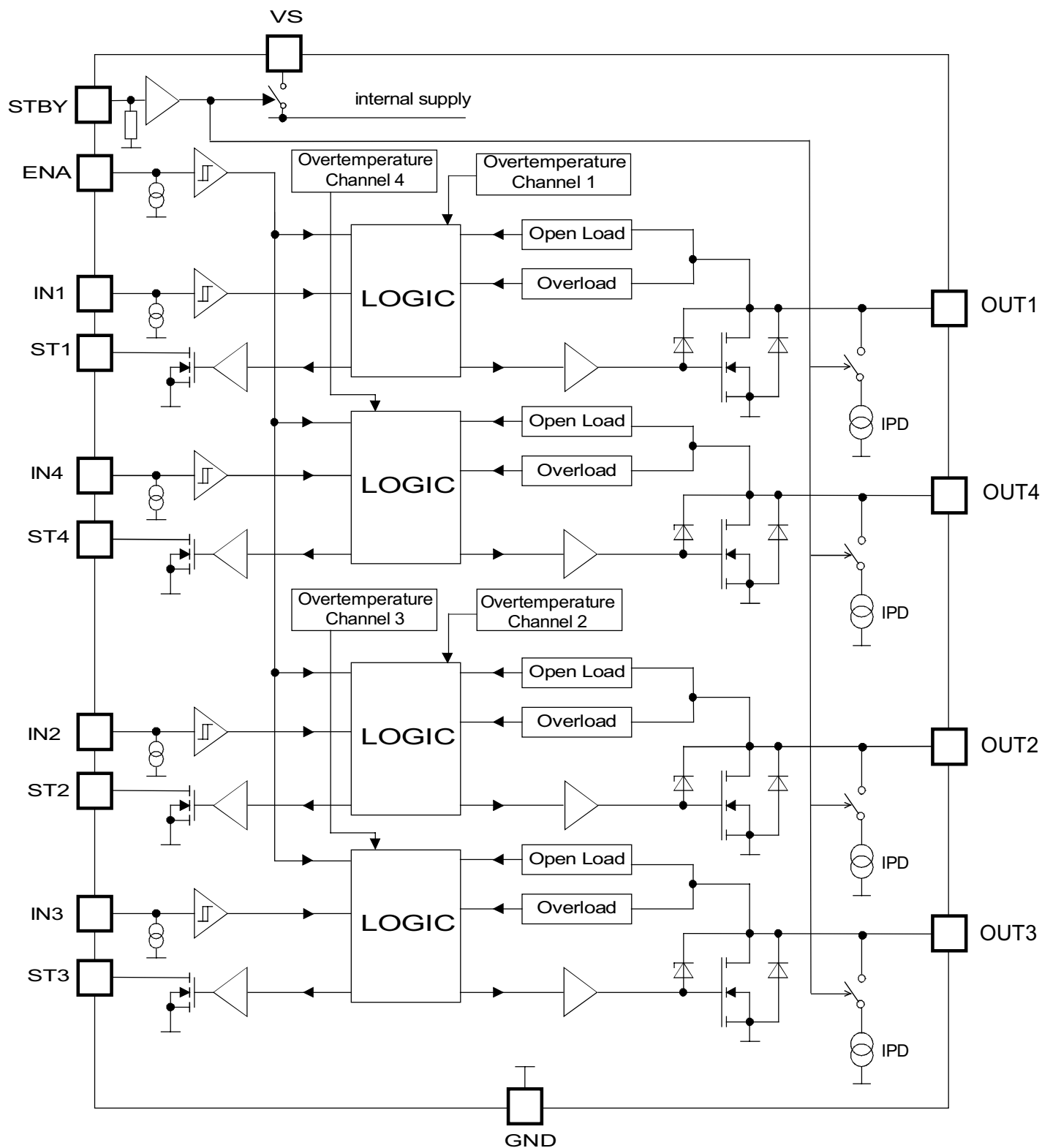
PG - DSO - 20 - 37

## Pin Description

Pin	Symbol	Function
1	GND	Ground
2	OUT1	Power Output channel 1
3	ST1	Status Output channel 1
4	IN4	Control Input channel 4
5	VS	Supply Voltage
6	STBY	Standby
7	IN3	Control Input channel 3
8	ST2	Status Output channel 2
9	OUT2	Power Output channel 2
10	GND	Ground
11	GND	Ground
12	OUT3	Power Output channel 3
13	ST3	Status Output channel 3
14	IN2	Control Input channel 2
15	GND	Ground Logic
16	ENA	Enable Input for all four channels
17	IN1	Control Input channel 1
18	ST4	Status Output channel 4
19	OUT4	Power Output channel 4
20	GND	Ground

Heat slug internally connected to ground pins

## Detailed Block Diagram



## Maximum Ratings for $T_j = -40^{\circ}\text{C}$ to $150^{\circ}\text{C}$

The maximum ratings may not be exceeded under any circumstances, not even momentarily and individually, as permanent damage to the IC will result.

Parameter	Symbol	Values	Unit
Supply voltage	$V_S$	-0.3 ... + 40	V
Continuous drain source voltage (OUT1...OUT4)	$V_{DS}$	40	V
Input voltage IN1 to IN4, ENA	$V_{IN}, V_{ENA}$	- 1.5... + 6	V
Input voltage STBY	$V_{STBY}$	- 0.3 ... + 40	
Status output voltage	$V_{ST}$	- 0.3 ... + 32	V
Operating temperature range	$T_j$	- 40 ... + 150	$^{\circ}\text{C}$
during clamping; $\Sigma t = 30$ min	$T_j$	175	
during clamping; $\Sigma t = 15$ min	$T_j$	190	
Storage temperature range	$T_{stg}$	- 55 ... + 150	
Output current per channel	$I_{D(lim)}$	overload shutdown	A
Output current at reversal supply	$I_{D\ 1,2}$ $I_{D\ 3,4}$	- 4 - 2	A
Status output current	$I_{ST}$	- 5 ... + 5	mA
Inductive load switch off energy (single pulse) $T_j = 25^{\circ}\text{C}$	$E_{AS}$	50	mJ
<b>Electrostatic Discharge Voltage (HBM) according to MIL STD 883D, method 3015.7 and EOS/ESD assn. Standard S5.1 – 1993</b> Output 1-4 Pins All other Pins	$V_{ESD}$	4000	V
	$V_{ESD}$	2000	V
Thermal resistance junction – case (die soldered on the frame)	$R_{thJC}$	2	K/W
Maximum operating lifetime (according to "Ambient thermal conditions")	$t_b$	10000	h

### Ambient thermal conditions

$T_{Ambient}$ temperature range	operating periods
-40 $^{\circ}\text{C}$	2 %
-20 $^{\circ}\text{C}$	10 %
25 $^{\circ}\text{C}$	24 %
60 $^{\circ}\text{C}$	34 %
80 $^{\circ}\text{C}$	24 %
100 $^{\circ}\text{C}$	5 %
> 120 $^{\circ}\text{C}$	1 %

## Electrical Characteristics

Parameter and Conditions $V_S = 4.8$ to $18$ V ; $T_j = -40$ °C to $+150$ °C (unless otherwise specified)	Symbol	Values			Unit
		min	typ	max	

### 1. Power Supply ( $V_S$ )

Supply current (Outputs ON)	$I_S$			8	mA
Supply current (Outputs OFF) $V_{ENA} = L$ , $V_{STBY} = H$	$I_S$			4	mA
Standby current $V_{STBY} = L$	$I_S$			10	μA
Operating voltage	$V_S$	4.8		32	V

### 2. Power Outputs

ON state resistance Channel 1,2 $I_D = 1$ A; $V_S \geq 9.5$ V	$T_j = 25$ °C $T_j = 150$ °C	$R_{DS(ON)}$		0.2	0.5	Ω
ON state resistance Channel 3,4 $I_D = 1$ A; $V_S \geq 9.5$ V	$T_j = 25$ °C $T_j = 150$ °C	$R_{DS(ON)}$		0.35	0.75	Ω
Z-Diode clamping voltage (OUT1...4) $I_D \geq 100$ mA		$V_{DS(AZ)}$	45		60	V
Pull down current $V_{STBY} = H$ , $V_{IN} = L$		$I_{PD}$	10	20	50	μA
Output Leakage Current $V_{STBY} = L$ $T_j = -40$ °C... $150$ °C wafer test at $25$ °C		$I_{DIK}$			5 1	μA μA
Output turn on delay time <sup>1</sup> $I_D = 1$ A		$t_{on}$	0	5	20	μs
Output turn off delay time <sup>1</sup> $I_D = 1$ A		$t_{off}$	0	10	30	
Output on fall time <sup>1</sup> $I_D = 1$ A		$t_{fall}$	3	10	30	
Output off rise time <sup>1</sup> $I_D = 1$ A		$t_{rise}$	3	10	30	
Overload switch-off delay time <sup>1</sup>		$t_{DSO}$	20		100	
Output off status delay time <sup>2</sup>		$t_D$	500	1200	3000	
Failure extension Time for Status Report		$t_{D-failure}$	500	1200	3000	
Input Suppression Time		$t_{D-IN}$	500	1200	3000	
Open Load (off) filtering Time <sup>2</sup>		$t_{fOL(off)}$	10	30	100	

### 3. Digital Inputs (IN1, IN2, IN3, IN4, ENA)

Input low voltage	$V_{INL}$	- 0.3		1.0	V
Input high voltage	$V_{INH}$	2.0		6.0	V
Input voltage hysteresis <sup>2</sup>	$V_{INHys}$	50	100		mV
Input pull down current $V_{IN} = 5$ V; $V_S \geq 6.5$ V	$I_{IN}$	10	30	60	μA
Enable pull down current $V_{ENA} = 5$ V; $V_S \geq 6.5$ V	$I_{ENA}$	10	20	40	μA

### 4. Digital Status Outputs (ST1 - ST4) Open Drain

Output voltage low $I_{ST} = 2$ mA	$V_{STL}$			0.5	V
Leakage current high	$I_{STH}$			2	μA

<sup>1</sup> See timing diagram, resistive load condition;  $V_S \geq 9$  V

<sup>2</sup> This parameter will not be tested but assured by design

## Electrical Characteristics

Parameter and Conditions $V_S = 4.8$ to $18$ V ; $T_j = -40$ °C to $+150$ °C (unless otherwise specified)	Symbol	Values			Unit
		min	typ	max	

### 5. Standby Input (STBY)

Input low voltage	$V_{STBY}$	0		1	V
Input high voltage	$V_{STBY}$	3.5		$V_S$	V
Input current $V_{STBY} = 18$ V	$I_{STBY}$			300	µA

### 6. Diagnostic Functions

Open load detection voltage $V_{ENA} = X, V_{IN} = L$	$V_S \geq 6.5$ V	$V_{DS(OL)}$	$0.3 \cdot V_S$	$0.33 \cdot V_S$	$0.36 \cdot V_S$	V
Open load detection current channel 1,2 $V_{ENA} = V_{IN} = H$	$V_S \geq 6.5$ V	$I_{D(OL) 1,2}$	100		240	mA
Open load detection current channel 3,4 $V_{ENA} = V_{IN} = H$	$V_S \geq 6.5$ V	$I_{D(OL) 3,4}$	100		240	mA
Overload Current channel 1, 2	$V_S \geq 6.5$ V	$I_{D(lim) 1,2}$	5	7.5		A
Overload Current channel 3, 4	$V_S \geq 6.5$ V	$I_{D(lim) 3,4}$	3	5		A
Overtemperature shutdown threshold <sup>2</sup>		$T_{th}$	170		200	°C
Hysteresis		$T_{hys}$		10		K
Pulse Width for static diagnostic output		$t_{IN}$			500	µs

<sup>2</sup> This parameter will not be tested but assured by design

## Application Description

This IC is especially designed to drive inductive loads (relays, electromagnetic valves). Integrated clamp-diodes limit the output voltage when inductive loads are discharged.

Four open-drain logic outputs indicate the status of the integrated circuit. The following conditions are monitored and signalled:

- Overloading of output (also shorted load to supply) in active mode
- Open and shorted load to ground in active and inactive mode
- Overtemperature

## Circuit Description

### Input Circuits

The control and enable inputs, both active high, consist of schmitt triggers with hysteresis. All inputs are provided with pull-down current sources. Not connected inputs are interpreted as low and the respective output stages are switched off.

In standby mode (STBY = LOW) the current consumption is greatly reduced.

The circuit is active when STBY = HIGH.

If the standby function is not used, it is allowed to connect the standby pin directly to VS.

Status Signals: The status signals are undefined for 2ms after a power up event or a STBY low to high transition.

### Output Stages

The four power outputs consist of DMOS-power transistors with open drains. The output stages are short circuit protected throughout the operating range. Each output has its own zenerclamp. This causes a voltage limitation at the power transistor when inductive loads are switched off.

Parallel to the DMOS transistors there are internal pull down current sources. They are provided to detect an open load condition in the off state. They will be disconnected in the standby mode.

Due to EMI measures there is an internal zenerclamp in parallel to the output stage. It gets active above 33V drain source voltage. This leads to an increasing leakage current up to 1 mA @  $V_{DS} = 40V$ .

### Protective Circuits

The outputs are protected against current overload and overtemperature. If the output current increases above the overload detection threshold  $I_{QO}$  for a longer time than  $t_{DSO}$  or the temperature increases above  $T_{th}$ , then the power transistor is immediately switched off. It remains off until the control signal at the input is switched off and on again.

### Fault Detection

The status outputs indicate the switching state of the output stage. Under normal conditions is: ST = low Output off; ST = high Output on. If an error occurs, the logic level of the status output is inverted, as listed in the diagnostic table.

If current overload or overtemperature occurs for a longer time than  $t_{DSO}$ , the fault condition is latched into an internal register and the output is shutdown. The reset is done by switching off the corresponding control input for a time longer than  $t_{D-IN}$ .

Open load is detected for all four channels in on and off mode.

In the on mode the load current is monitored. If it drops below the specified threshold value  $I_{QU}$  then an open load condition is detected.

In the off mode, the output voltage is monitored. An open load condition is detected when the output voltage of a given channel is below the threshold  $V_{DS(OL)}$ , which is typ. 33 % of the supply voltage  $V_S$ . To prevent an open load diagnosis in case of transient Voltages on the outputs the open load detection in off mode uses a filter of typ. 30 $\mu$ s.

### Status output at pulse width operation

If the input is operated with a pulsed signal, the status does not follow each single pulse of the input signal. An internal delay  $t_D$  of typ. 1.2ms (min 500  $\mu$ s) enables a continuous status output signal. See the timing diagrams on the following pages for further information.

This internal status delay simplifies diagnostic software for pwm applications.

## Diagnostic Table

In general the status follows the input signal in normal operating conditions.

If any error is detected the status is inverted.

Operating Condition	Standby Input	Enable Input	Control Input	Power Output	Status Output
	STBY	ENA	IN	Q	ST
Standby	L	X	X	off	H
Normal function	H	L	X	off	L
	H	H	L	off	L
	H	H	H	ON	H
Open load or short to ground	H	L	L	off	H
	H	L	H	off	H
	H	H	L	off	H
	H	H	H	ON	L
Overload or short to supply <sup>1)</sup> reset latch <sup>2)</sup>	H	H	H	off	L
	H	H	H $\rightarrow$ L	off	L
	H	L	X	off	L
Overtemperature <sup>1)</sup> reset latch <sup>2)</sup>	H	H	H	off	L
	H	H	H $\rightarrow$ L	off	L
	H	L	X	off	L

Note 1) : overload/short-to-supply/overtemperature - events shorter than min. time  $t_{DSO}$  specified in 2.10 will not be latched and not reported at the status pin.

## Failure Situations and Status Report

**Overtemperature**  
1.....overtemperature  
0.....normal cond.

**ENA**  
1....enabled  
0... disabled

**Input**  
1....On  
0... Off

**Overload**  
0.....overload  
1.....normal cond.

**Open load "off"**  
1.....open load  
0.....normal cond.

**Open load "on"**  
0.....open load  
1.... normal cond.

**Gate Driver**  
1... Output  
0....Output  
...Output

**Delay D**  
IN  
OUT  
 $t_D$   
1,2ms typ.

**Delay 60µs**  
IN  
OUT  
 $t_D$   
60µs typ.

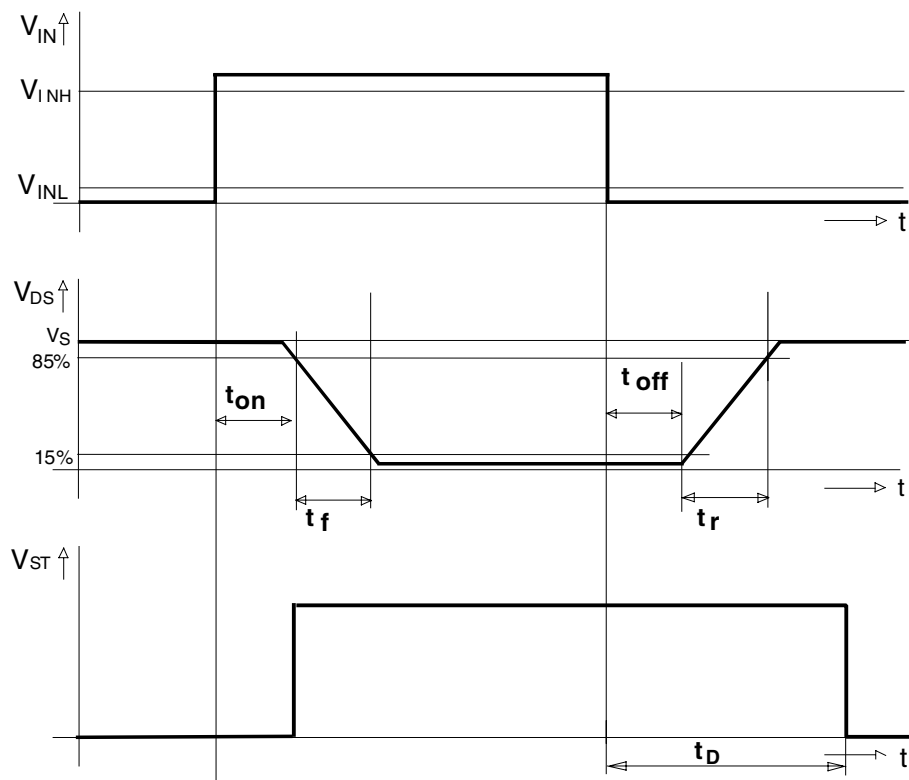
**Status**  
0....High  
1.....Low

**Timing Diagrams:**

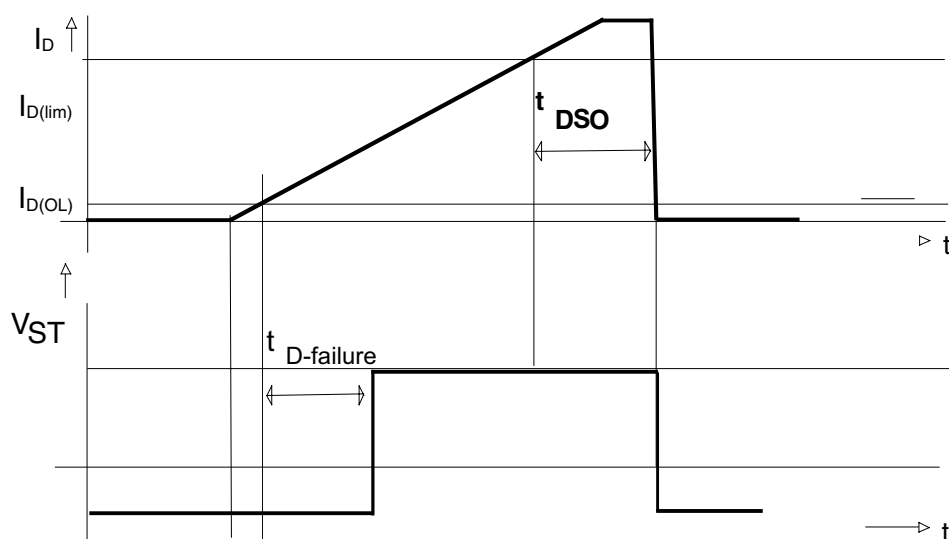
- Delay D (Top):** IN transitions from low to high. OUT transitions from low to high after a delay  $t_D$ . The delay is 1,2ms typ.
- Delay 60µs (Bottom):** IN transitions from low to high. OUT transitions from low to high after a delay  $t_D$ . The delay is 60µs typ.

## Timing Diagrams

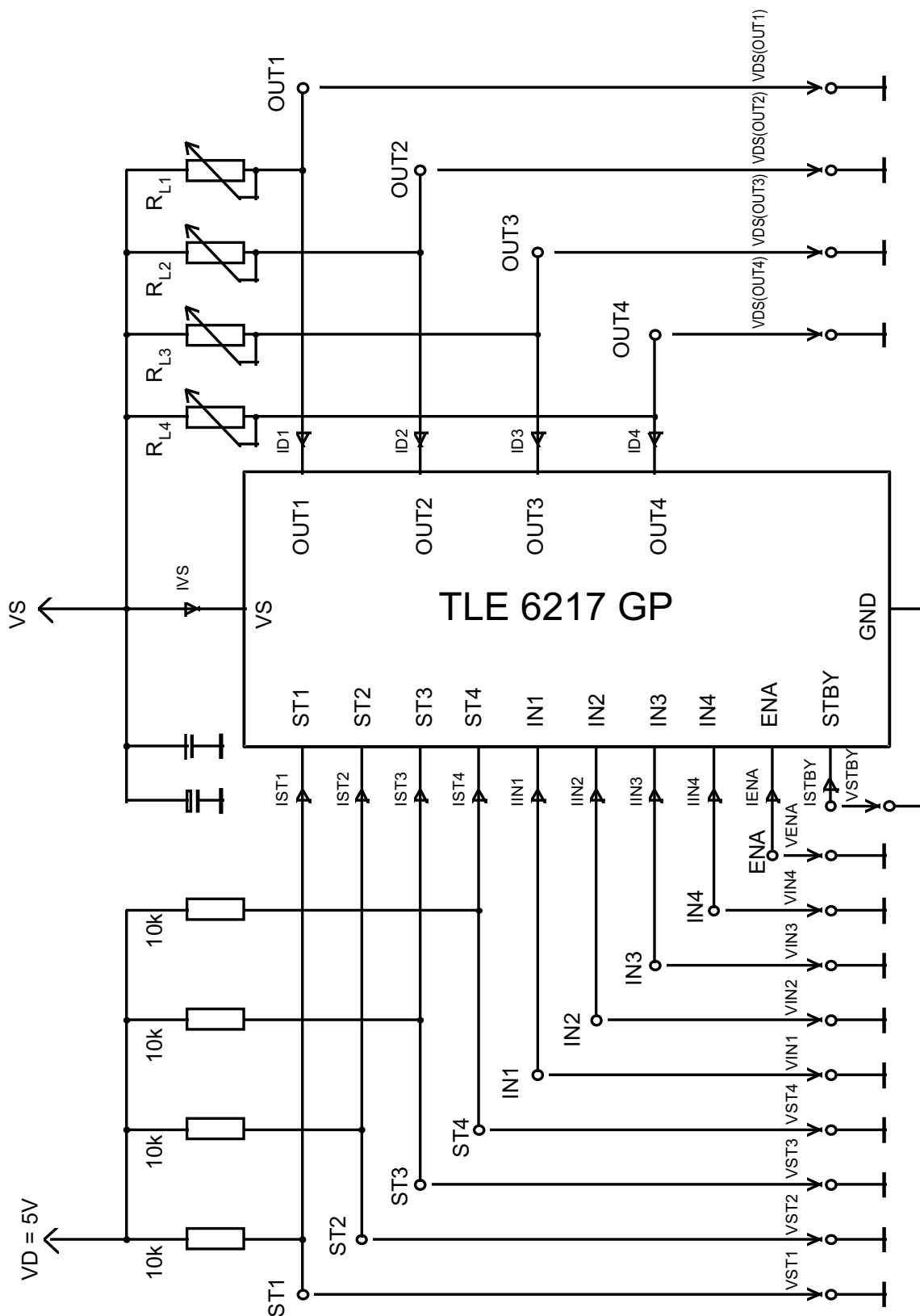
### Output Slope


**FIG. 1**

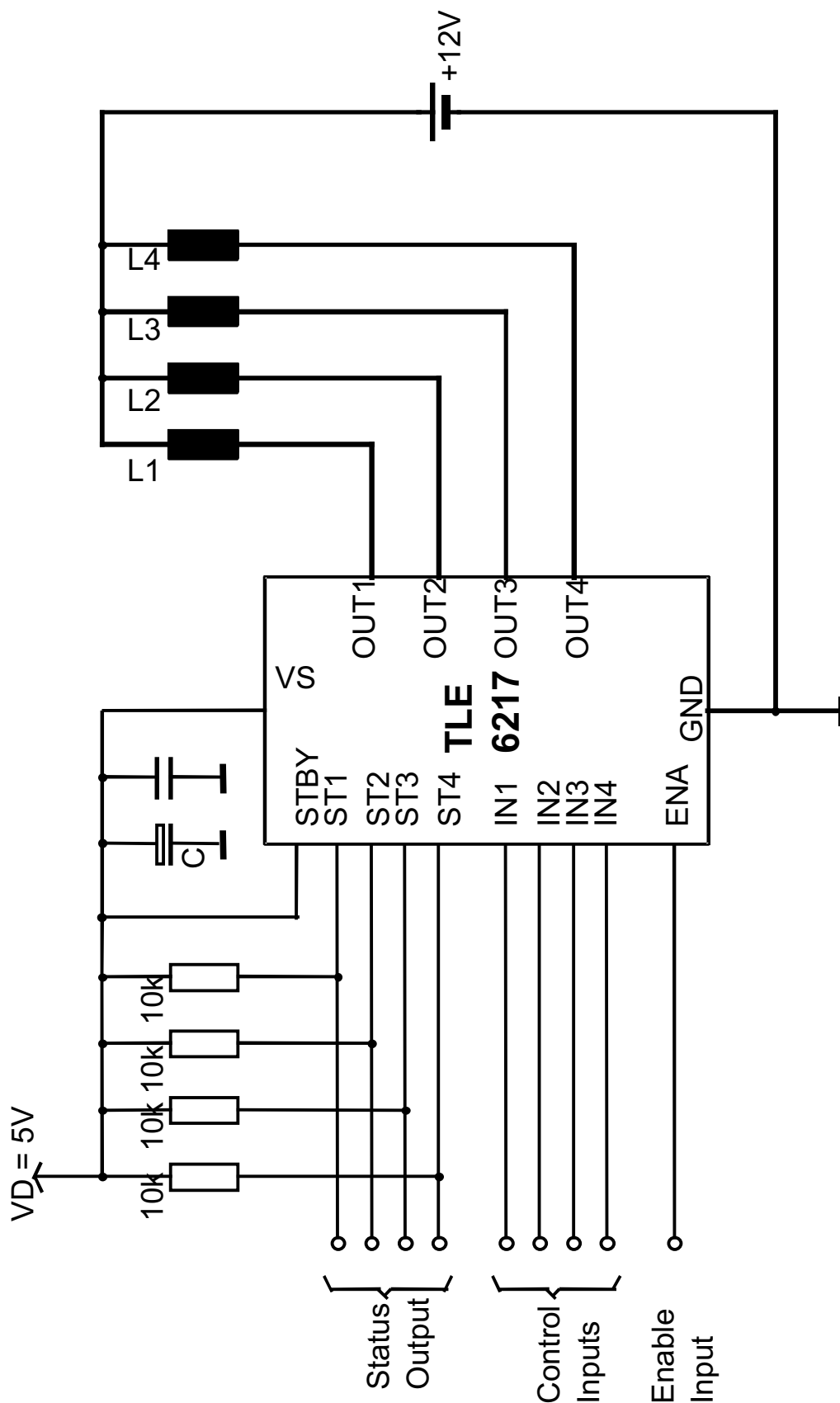
### Overload Switch OFF Delay


**FIG. 2**

## Test Circuit



## Application Circuit



The blocking capacitor C is recommended to avoid critical negative voltage spikes on VS in case of battery interruption during OFF-commutation.

## Timing Diagrams of Diagnostic with Pulsed Input Signal

Normal condition, resistive load, pulsed input signal

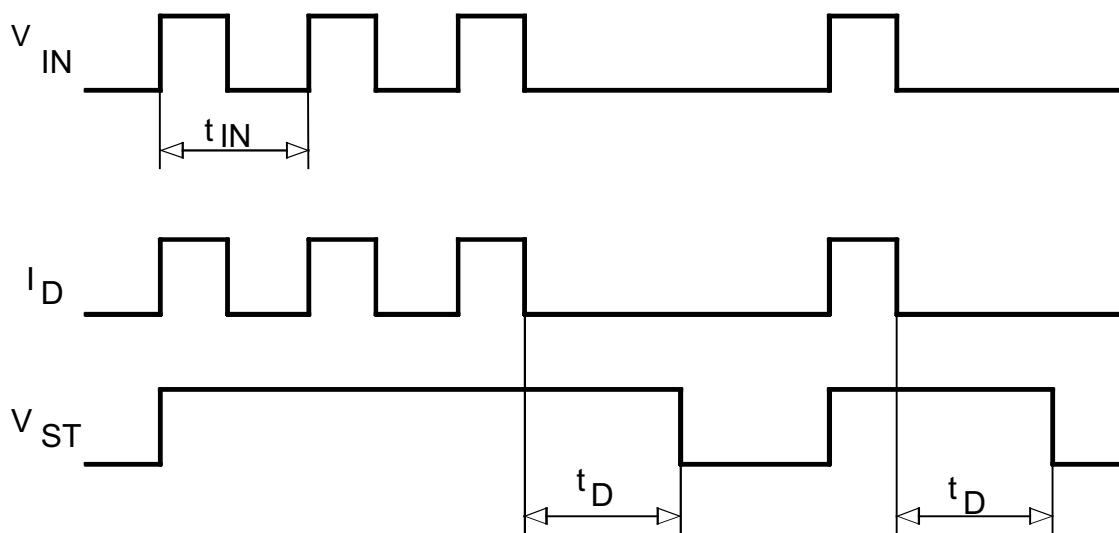
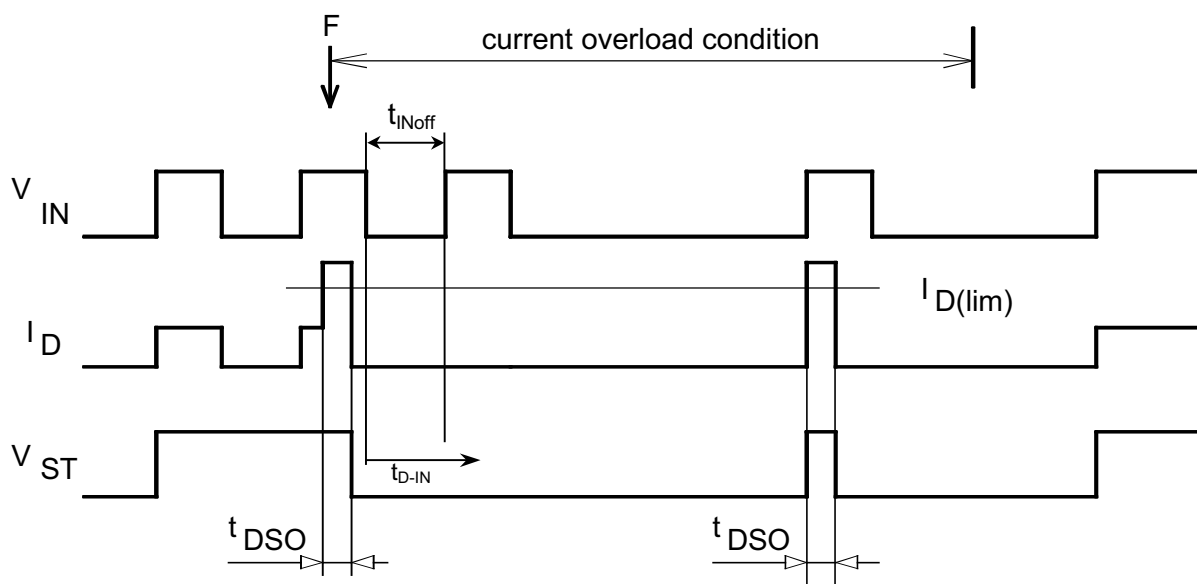


Fig. 3

### Current Overload



$t_{INoff} < t_{D-IN}$  : Input suppression time avoids a restart after overtemperature

Fig. 4

## Diagnostic status output at different open load current conditions

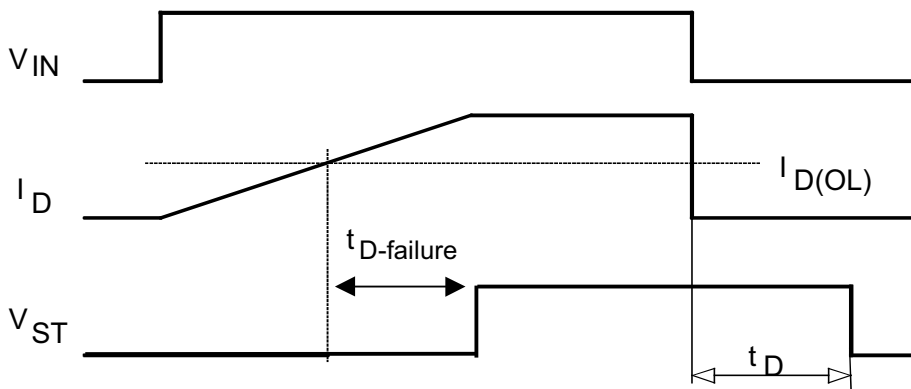
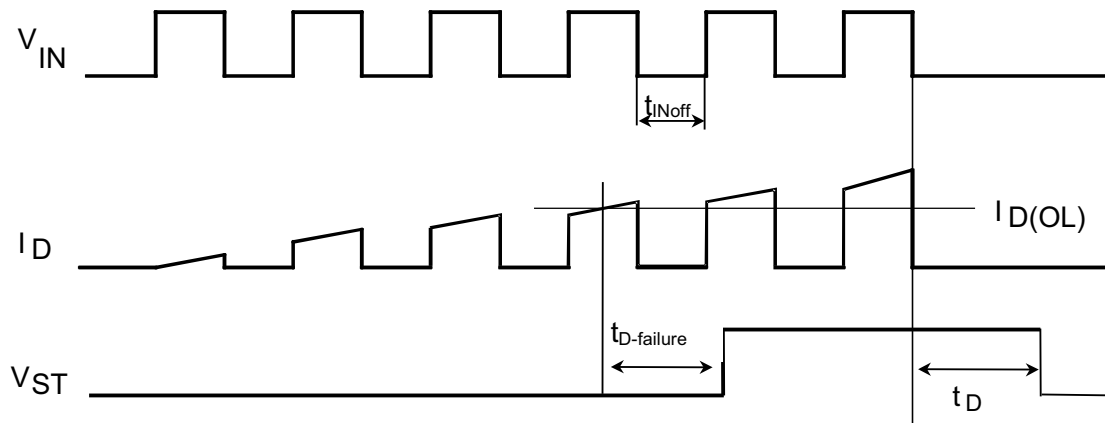
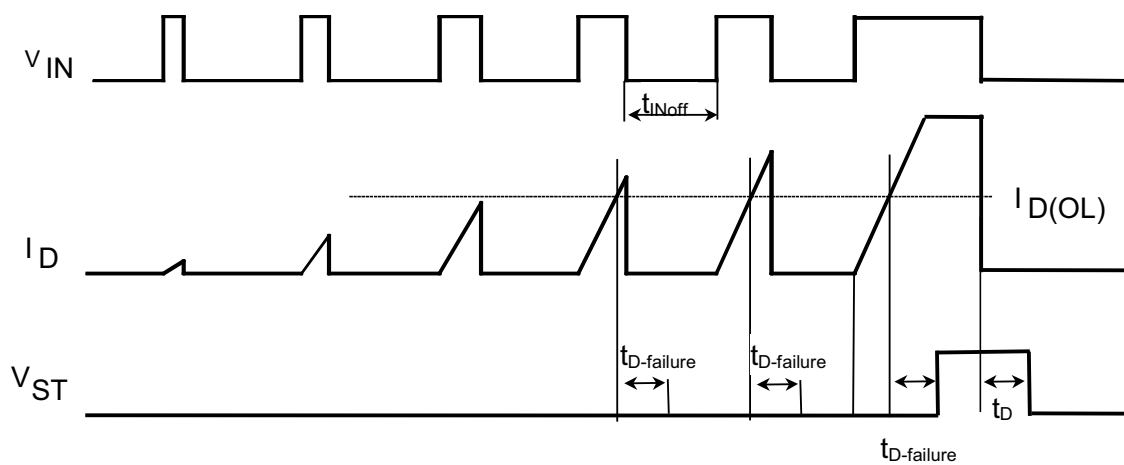


Fig. 5



$t_{INoff} < t_D$  leads to a static status signal

Fig. 6



$t_{INoff} > t_D$  : Intermittent status signal

Fig. 7

### Normal operation, followed by open load condition

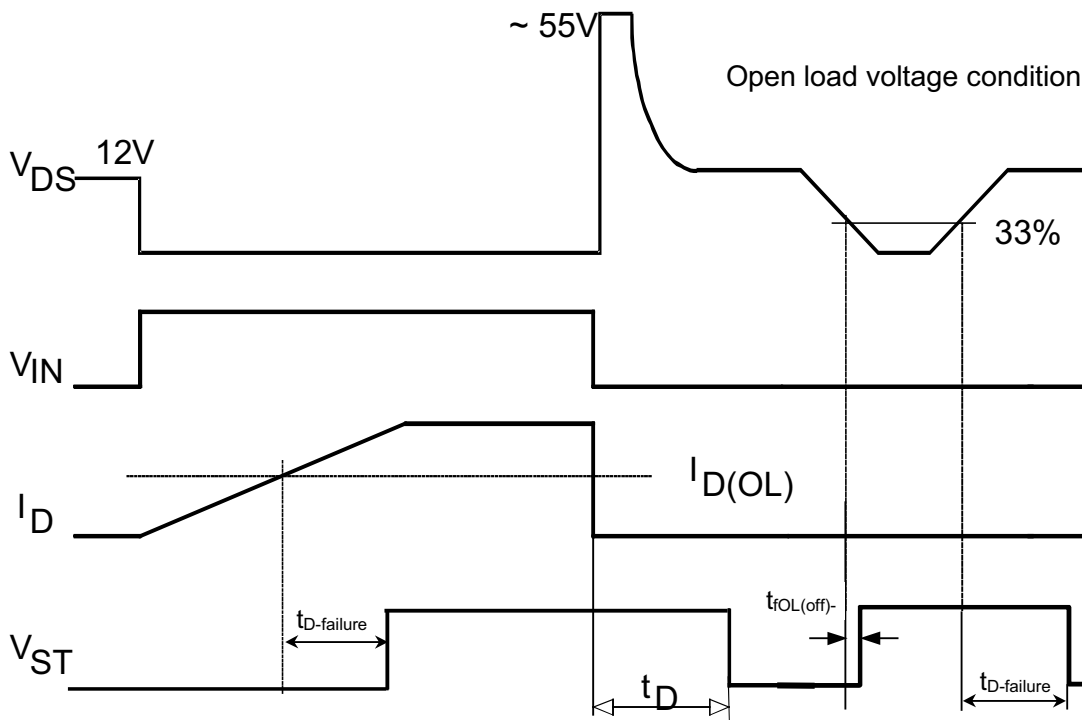


Fig. 8

### Overtemperature

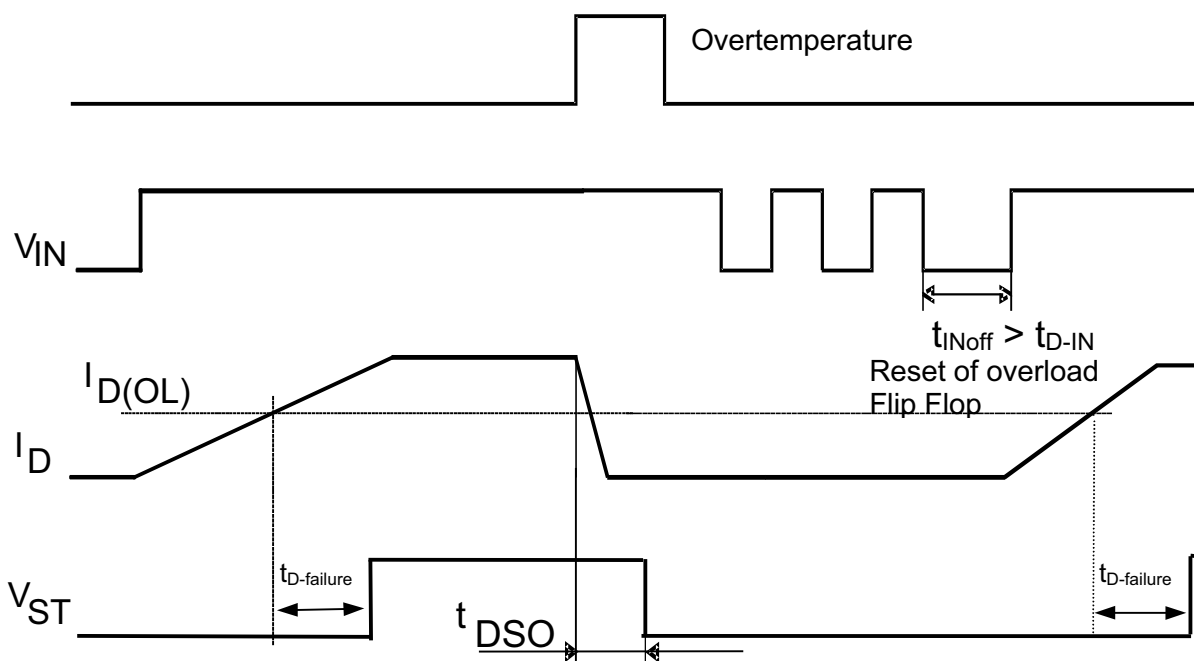
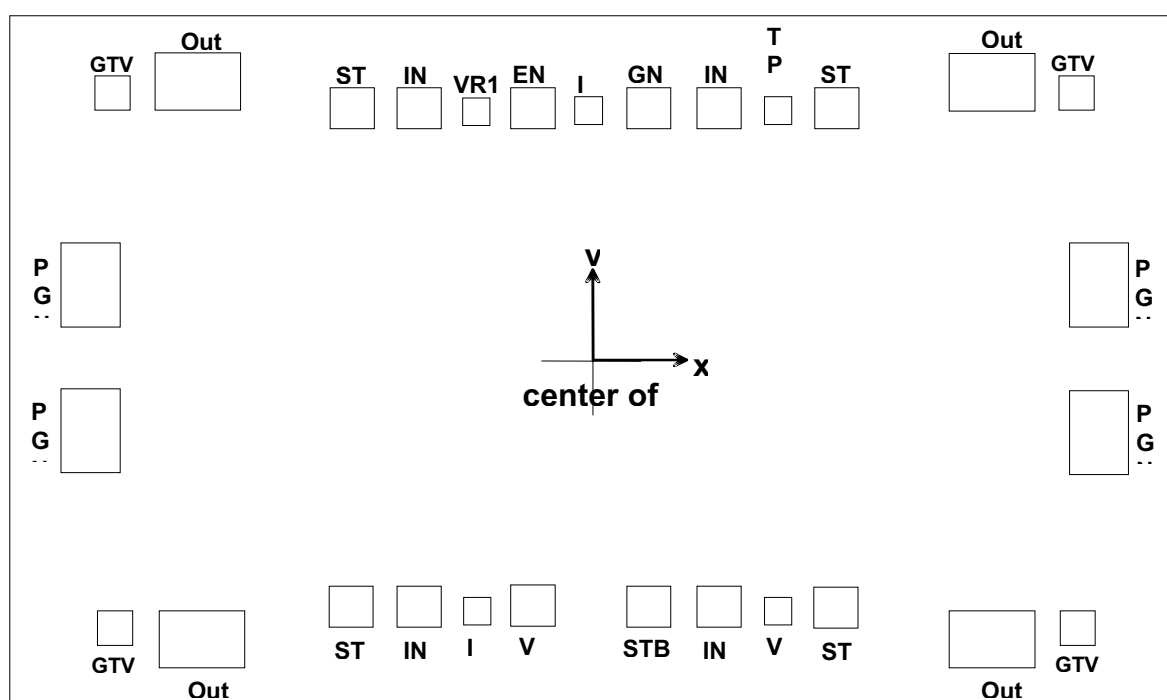


Fig. 9

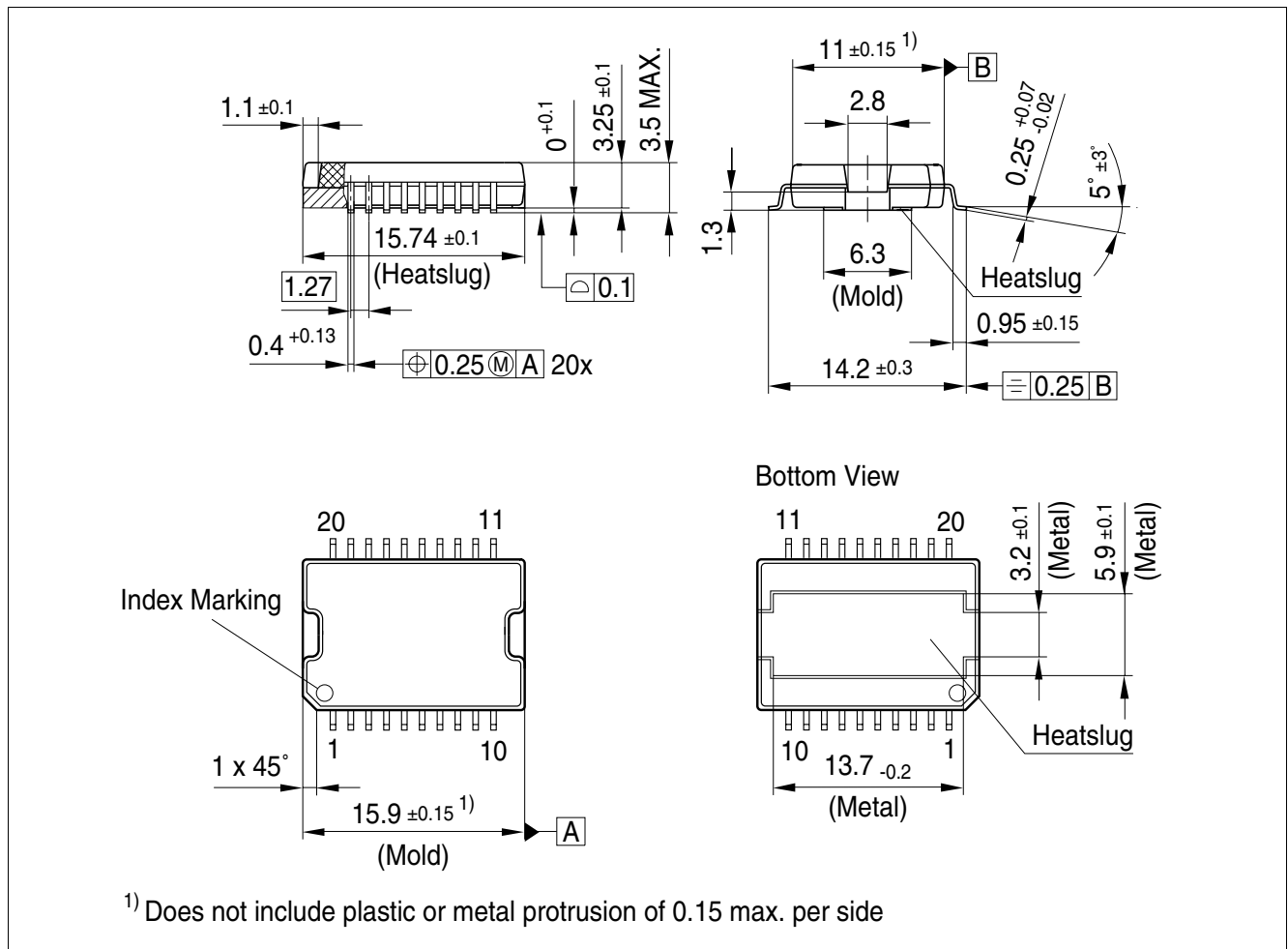
## Ordering code

Type	Ordering Code	Package
TLE6217 G	on request	P - DSO - 20 – 12
TLE6217 C	on request	Bare dice on wafer

## Pad Assignment



## Package Outlines



**Figure 1 PG-DSO-20-37** (Please Insert Package Long Name!)

### Green Product (RoHS compliant)

To meet the world-wide customer requirements for environmentally friendly products and to be compliant with government regulations the device is available as a green product. Green products are RoHS-Compliant (i.e. Pb-free finish on leads and suitable for Pb-free soldering according to IPC/JEDEC J-STD-020).

For further information on alternative packages, please visit our website:

<http://www.infineon.com/packages>.

Dimensions in mm

## 1 Revision History

Revision	Date	Changes
6.1	2008-04-04	Initial version of RoHS-compliant derivate of TLE6217G Page 1: AEC certified statement added Page 1 and 17: added RoHS compliance statement and Green product feature Page 1 and 17: Package changed to RoHS compliant version Page 18-19: added Revision History, updated Legal Disclaimer

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